V_{CC2} L

9 3,4EN

600-mA Output Current Capability Per Driver

- Pulsed Current 1.2-A Per Driver
- Output Clamp Diodes for Inductive Transient Suppression
- Wide Supply Voltage Range 4.5 V to 36 V
- Separate Input-Logic Supply
- Thermal Shutdown
- Internal ESD Protection
- High-Noise-Immunity Inputs
- Functional Replacement for SGS L293D

description

The L293D is a quadruple high-current half-H driver designed to provide bidirectional drive currents of up to 600-mA at voltages from 4.5 V to 36 V. It is designed to drive inductive loads such as relays, solenoids, dc and bipolar stepping motors, as well as other high-current/high-voltage loads in positive-supply applications.

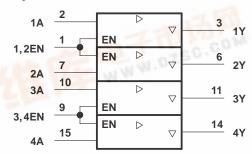
All inputs are TTL-compatible. Each output is a complete totem-pole drive circuit with a Darlington transistor sink and a pseudo-Darlington source. Drivers are enabled in pairs with drivers 1 and 2 enabled by 1,2EN and drivers 3 and 4 enabled by 3,4EN. When an enable input is high, the associated drivers are enabled, and their outputs are active and in phase with their inputs. External high-speed output clamp diodes should be used for inductive transient suppression. When the enable input is low, those drivers are disabled, and their outputs are off and in a high-impedance state. With the proper data inputs, each pair of drivers form a full-H (or bridge) reversible drive suitable for solenoid or motor applications.

A V_{CC1} terminal, separate from V_{CC2} , is provided for the logic inputs to minimize device power dissipation.

The L293D is designed for operation from 0°C to 70°C.

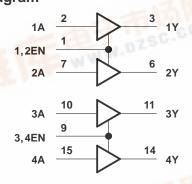
NE PACKAGE (TOP VIEW) 1,2EN 16 VCC1 15 AA 1A 1Y [3 14 4Y HEAT SINK AND 4 **HEAT SINK AND** 12 GROUND **GROUND** 5 2Y 6 11 3Y 2A 10 3A

logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram



FUNCTION TABLE (each driver)

	INPU	JTS‡	OUTPUT			
	Α	EN	Y			
1	Н	Н	Н			
ı	L	Н	L			
ı	Χ	L	Z			

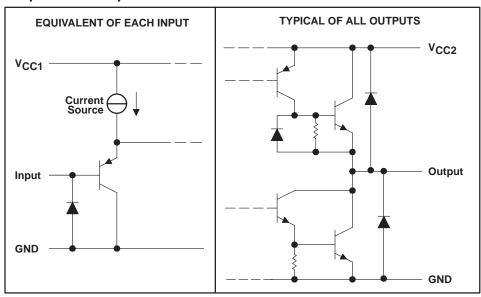
H = high-level, L = low level,

X = irrelevant, Z = high-impedance (off)

† In the thermal shutdown mode, the output is in the high-impedance state regardless of the input levels.



schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Logic supply voltage range, V _{CC1} (see Note 1)
Output supply voltage range, V _{CC2}
Input voltage range, V _I
Output voltage range, V _O –3 V to V _{CC2} + 3 V
Peak output current (nonrepetitive, $t \le 100 \mu s$)
Continuous output current, I _O ±600 mA
Continuous total dissipation at (or below) 25°C free-air temperature (see Notes 2 and 3) 2075 mW
Continuous total dissipation at 80°C case temperature (see Note 3)
Operating case or virtual junction temperature range, T _J –40°C to 150°C
Storage temperature range, T _{stq} –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds

NOTES: 1. All voltage values are with respect to the network ground terminal.

- 2. For operation above 25°C free-air temperature, derate linearly at the rate of 16.6 mW/°C.
- 3. For operation above 25°C case temperature, derate linearly at the rate of 71.4 mW/°C. Due to variations in individual device electrical characteristics and thermal resistance, the built-in thermal overload protection may be activated at power levels slightly above or below the rated dissipation.

recommended operating conditions

		MIN	MAX	UNIT
Logic supply voltage, V _{CC1}		4.5	7	V
Output supply voltage, V _{CC2}		V _{CC1}	36	V
High level input valtage V.	V _{CC1} ≤ 7 V	2.3	VCC1	V
High-level input voltage, VIH	V _{CC1} ≥ 7 V	2.3	7	
ow-level input voltage, V _{IL}		-0.3†	1.5	V
Operating free-air temperature, T _A		0	70	°C

[†] The algebraic convention, in which the least positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels.



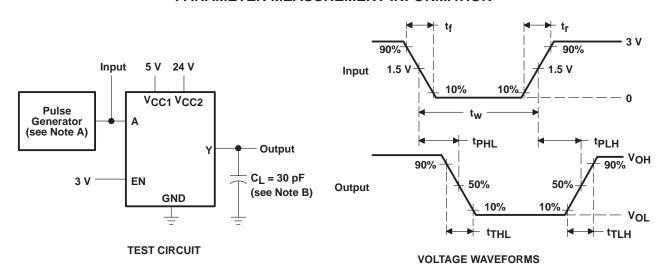
electrical characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

PARAMETER			TEST CONDITIONS		MIN	TYP	MAX	UNIT	
VOH	High-level output voltage		$I_{OH} = -0.6 \text{ A}$		V _{CC2} -1.8	V _{CC2} -1.4		V	
VOL	Low-level output voltage		$I_{OL} = 0.6 A$	1		1.2	1.8	V	
Vокн	VOKH High-level output clamp voltage IO		$I_{OK} = -0.6 \text{ A}$			V _{CC2} +1.3		V	
VOKL	VOKL Low-level output clamp voltage		$I_{OK} = -0.6 \text{ A}$			1.3		V	
1	High-level input current	А	V _I = 7 V			0.2	100	μΑ	
lін		EN				0.2	±10		
1	Low-level input current	Α	V _I = 0			-3	-10	μA mA	
IL		EN				-2	-100		
	Logic supply current		IO = 0	All outputs at high level		13	22		
ICC1				All outputs at low level		35	60		
				All outputs at high impedance		8	24		
	Output supply current		I _O = 0	All outputs at high level		14	24		
I _{CC2}				All outputs at low level		2	6	mA	
				All outputs at high impedance		2	4		

switching characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	Propagation delay time, low-to-high-level output from A input			800		ns
tPHL	Propagation delay time, high-to-low-level output from A input	C _I = 30 pF, See Figure 1		400		ns
tTLH	Transition time, low-to-high-level output	CL = 30 pr, See rigule i		300		ns
tTHL	Transition time, high-to-low-level output			300		ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: $t_{\text{f}} \leq$ 10 ns, t_{W} = 10 μ s, PRR = 5 kHz, Z_{O} = 50 Ω .

B. C_L includes probe and jig capacitance.

Figure 1. Test Circuit and Voltage Waveforms



APPLICATION INFORMATION

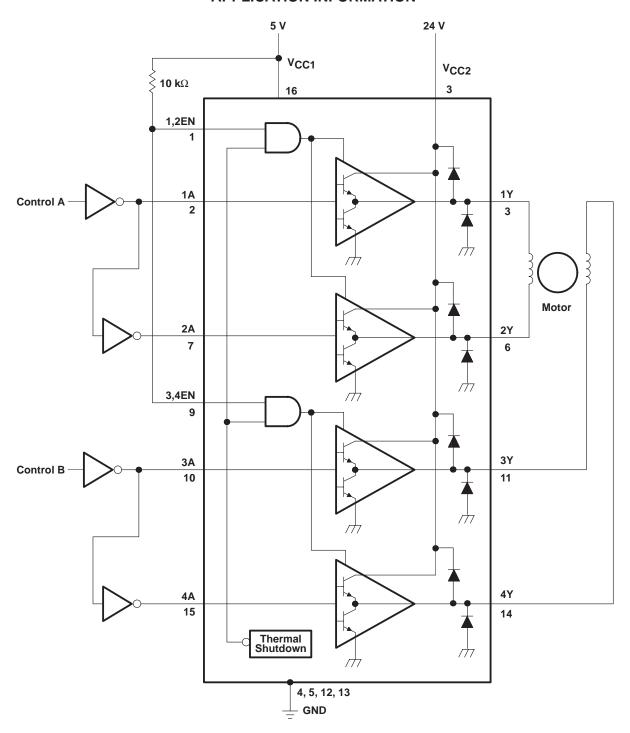


Figure 2. Two-Phase Motor Driver



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